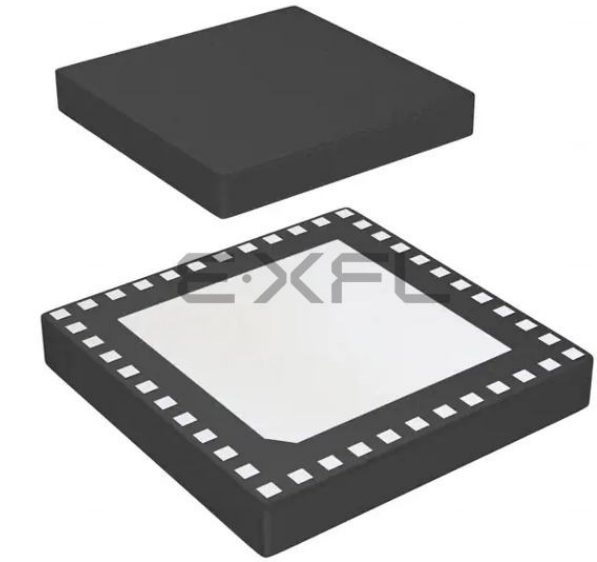
# Microchip Technology - DSPIC33FJ16GS504-H/TL Datasheet



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## What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

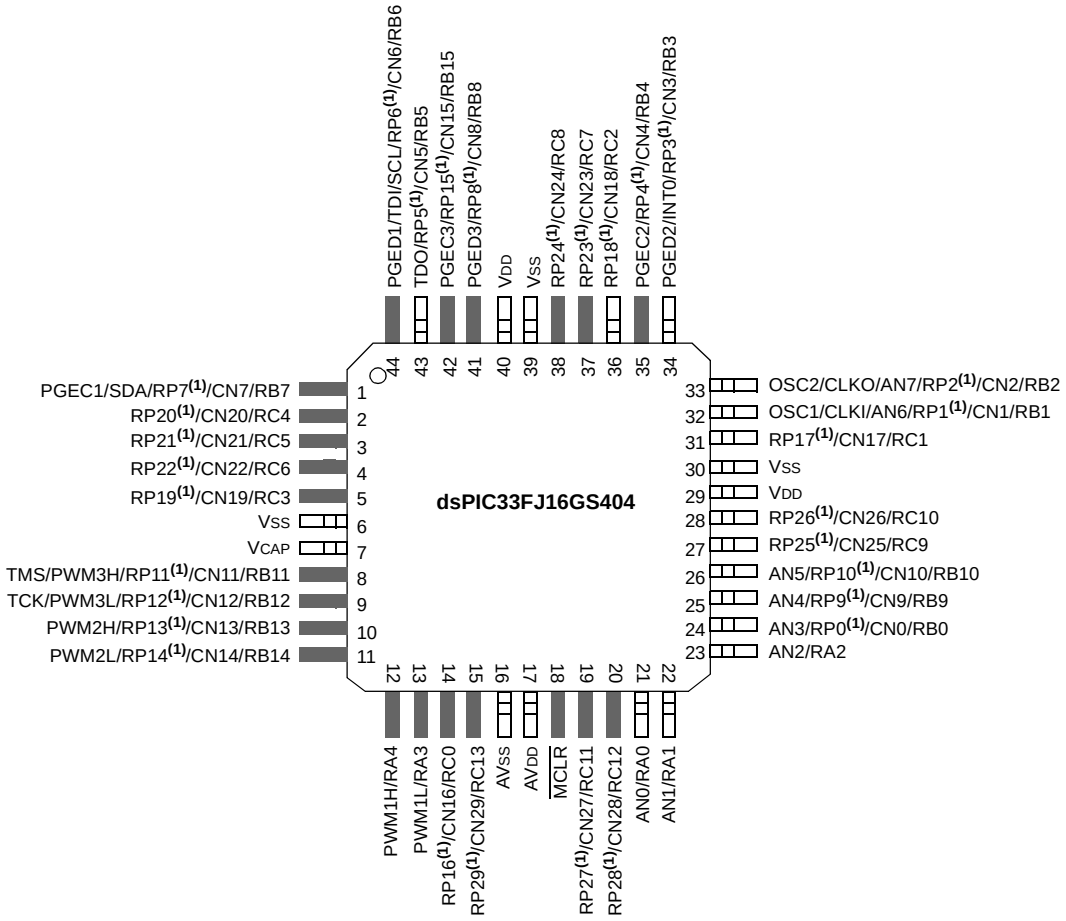
## Applications of "Embedded - Microcontrollers"

| Details | |
|---|---|
| Product Status | Active |
| Core Processor | dsPIC |
| Core Size | 16-Bit |
| Speed | 40 MIPs |
| Connectivity | I²C, IrDA, LINbus, SPI, UART/USART |
| Peripherals | Brown-out Detect/Reset, POR, PWM, WDT |
| Number of I/O | 35 |
| Program Memory Size | 16KB (16K x 8) |
| Program Memory Type | FLASH |
| EEPROM Size | - |
| RAM Size | 2K x 8 |
| Voltage - Supply (Vcc/Vdd) | 3V ~ 3.6V |
| Data Converters | A/D 24x10b; D/A 4x10b |
| Oscillator Type | Internal |
| Operating Temperature | -40°C ~ 150°C (TA) |
| Mounting Type | Surface Mount |
| Package / Case | 44-VFTLA Exposed Pad |
| Supplier Device Package | 44-VTLA (6x6) |
| Purchase URL | https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gs504-h-tl |

## Pin Diagrams (Continued)

**44-Pin TQFP**

■ = Pins are up to 5V tolerant




**Note 1:** The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

### 4.6.2 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the program space without going through data space. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a program space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit wide word address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space that contains the least significant data word. TBLRDH and TBLWTH access the space that contains the upper data byte.

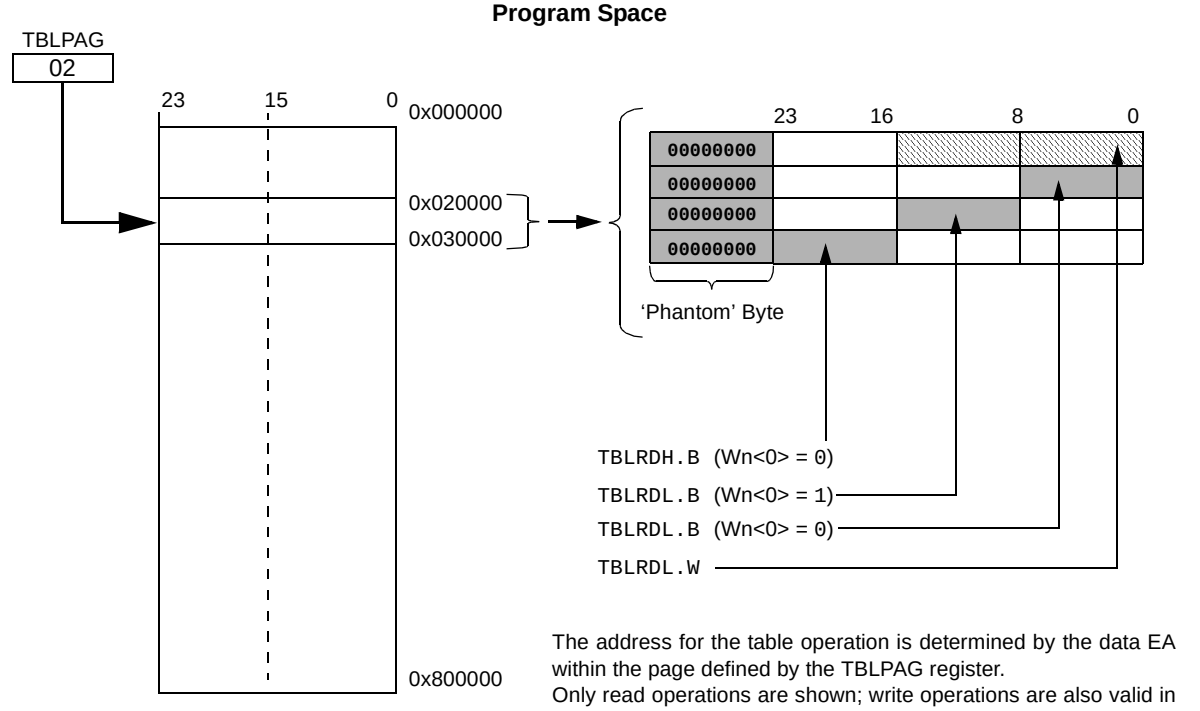
Two table instructions are provided to move byte or word-sized (16-bit) data to and from program space. Both function as either byte or word operations.

- TBLRDL (Table Read Low):
  - In Word mode, this instruction maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).
  - In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when byte select is '1'; the lower byte is selected when it is '0'.
- TBLRDH (Table Read High):
  - In Word mode, this instruction maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the 'phantom byte', will always be '0'.
  - In Byte mode, this instruction maps the upper or lower byte of the program word to D<7:0> of the data address, in the TBLRDL instruction. The data is always '0' when the upper 'phantom' byte is selected (Byte Select = 1).

Similarly, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

**FIGURE 4-10: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS**




The address for the table operation is determined by the data EA within the page defined by the TBLPAG register.
Only read operations are shown; write operations are also valid in the user memory area.

**NOTES:**

## 5.0 FLASH PROGRAM MEMORY

**Note 1:** This data sheet summarizes the features of the dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Flash Programming"** (DS70191) in the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

**2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

- In-Circuit Serial Programming™ (ICSP™) programming capability
- Run-Time Self-Programming (RTSP)

ICSP allows a dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 device to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx, and three other lines for power (VDD), ground (VSS) and Master Clear ($\overline{MCLR}$). This allows customers to manufacture boards with unprogrammed devices and then program the Digital Signal Controller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using TBLRD (Table Read) and TBLWT (Table Write) instructions. With RTSP, the user application can write program memory data, either in blocks or 'rows' of 64 instructions (192 bytes) at a time, or a single program memory word, and erase program memory in blocks or 'pages' of 512 instructions (1536 bytes) at a time.

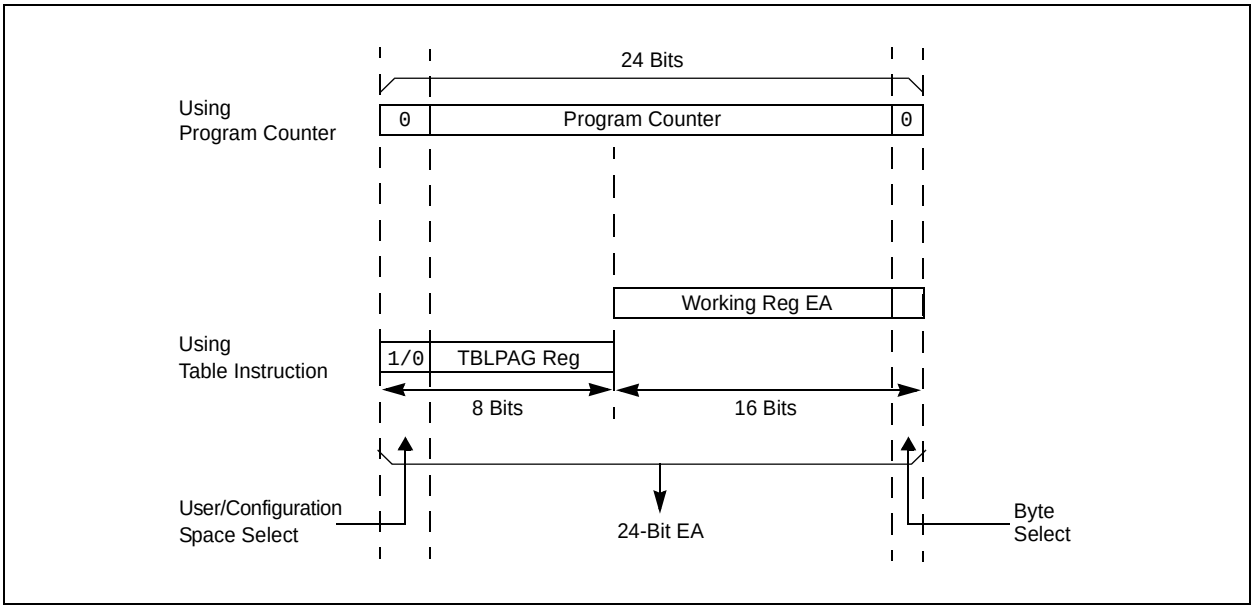
### 5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the Table Read and Table Write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits<7:0> of the TBLPAG register and the Effective Address (EA) from a W register specified in the table instruction, as shown in Figure 5-1.

The TBLRDL and the TBLWTL instructions are used to read or write to bits<15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits<23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

**FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS**



### 6.8.2 UNINITIALIZED W REGISTER RESET

Any attempt to use the Uninitialized W register as an Address Pointer will reset the device. The W register array (with the exception of W15) is cleared during all Resets and is considered uninitialized until written to.

### 6.8.3 SECURITY RESET

If a Program Flow Change (PFC) or Vector Flow Change (VFC) targets a restricted location in a protected segment (boot and secure segment), that operation will cause a Security Reset.

The PFC occurs when the Program Counter is reloaded as a result of a call, jump, computed jump, return, return from subroutine or other form of branch instruction.

The VFC occurs when the Program Counter is reloaded with an interrupt or trap vector.

Refer to **Section 21.8 "Code Protection and CodeGuard™ Security"** for more information on Security Reset.

## 6.9 Using the RCON Status Bits

The user application can read the Reset Control (RCON) register after any device Reset to determine the cause of the Reset.

| | |
|---|---|
| **Note:** | The status bits in the RCON register should be cleared after they are read so that the next RCON register value after a device Reset will be meaningful. |

Table 6-3 provides a summary of the Reset flag bit operation.

**TABLE 6-3: RESET FLAG BIT OPERATION**

| Flag Bit | Set by: | Cleared by: |
|---|---|---|
| **TRAPR** (RCON<15>) | Trap conflict event | POR, BOR |
| **IOPWR** (RCON<14>) | Illegal opcode or Uninitialized W register access or Security Reset | POR, BOR |
| **CM** (RCON<9>) | Configuration Mismatch | POR, BOR |
| **EXTR** (RCON<7>) | $\overline{\text{MCLR}}$ Reset | POR |
| **SWR** (RCON<6>) | RESET instruction | POR, BOR |
| **WDTO** (RCON<4>) | WDT time-out | PWRSAV instruction, CLRWDT instruction, POR, BOR |
| **SLEEP** (RCON<3>) | PWRSAV #SLEEP instruction | POR, BOR |
| **IDLE** (RCON<2>) | PWRSAV #IDLE instruction | POR, BOR |
| **BOR** (RCON<1>) | POR, BOR | — |
| **POR** (RCON<0>) | POR | — |

**Note:** All Reset flag bits can be set or cleared by user software.

**REGISTER 7-21: IPC2: INTERRUPT PRIORITY CONTROL REGISTER 2**

| U-0 | R/W-1 | R/W-0 | R/W-0 | U-0 | R/W-1 | R/W-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| — | U1RXIP2 | U1RXIP1 | U1RXIP0 | — | SPI1IP2 | SPI1IP1 | SPI1IP0 |
| bit 15 | | | | | | | bit 8 |

| U-0 | R/W-1 | R/W-0 | R/W-0 | U-0 | R/W-1 | R/W-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| — | SPI1EIP2 | SPI1EIP1 | SPI1EIP0 | — | T3IP2 | T3IP1 | T3IP0 |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as ‘0’ | |
| -n = Value at POR | ‘1’ = Bit is set | ‘0’ = Bit is cleared | x = Bit is unknown |

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **U1RXIP<2:0>:** UART1 Receiver Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **SPI1IP<2:0>:** SPI1 Event Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **SPI1EIP<2:0>:** SPI1 Error Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **T3IP<2:0>:** Timer3 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

**REGISTER 7-28: IPC23: INTERRUPT PRIORITY CONTROL REGISTER 23**

| U-0 | R/W-1 | R/W-0 | R/W-0 | U-0 | R/W-1 | R/W-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| — | PWM2IP2 | PWM2IP1 | PWM2IP0 | — | PWM1IP2 | PWM1IP1 | PWM1IP0 |
| bit 15 | | | | | | | bit 8 |

| U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
|---|---|---|---|---|---|---|---|
| — | — | — | — | — | — | — | — |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as ‘0’ | |
| -n = Value at POR | ‘1’ = Bit is set | ‘0’ = Bit is cleared | x = Bit is unknown |

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **PWM2IP<2:0>:** PWM2 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **PWM1IP<2:0>:** PWM1 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7-0 **Unimplemented:** Read as ‘0’

**REGISTER 10-3: RPINR3: PERIPHERAL PIN SELECT INPUT REGISTER 3**

| U-0 | U-0 | R/W-1 | R/W-1 | R/W-1 | R/W-1 | R/W-1 | R/W-1 |
|---|---|---|---|---|---|---|---|
| — | — | T3CKR5 | T3CKR4 | T3CKR3 | T3CKR2 | T3CKR1 | T3CKR0 |
| bit 15 | | | | | | | bit 8 |

| U-0 | U-0 | R/W-1 | R/W-1 | R/W-1 | R/W-1 | R/W-1 | R/W-1 |
|---|---|---|---|---|---|---|---|
| — | — | T2CKR5 | T2CKR4 | T2CKR3 | T2CKR2 | T2CKR1 | T2CKR0 |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as ‘0’ | |
| -n = Value at POR | ‘1’ = Bit is set | ‘0’ = Bit is cleared | x = Bit is unknown |

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **T3CKR<5:0>:** Assign Timer3 External Clock (T3CK) to the Corresponding RPn Pin bits

111111 = Input tied to Vss
100011 = Input tied to RP35
100010 = Input tied to RP34
100001 = Input tied to RP33
100000 = Input tied to RP32
•
•
•
00000 = Input tied to RP0

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **T2CKR<5:0>:** Assign Timer2 External Clock (T2CK) to the Corresponding RPn Pin bits

111111 = Input tied to Vss
100011 = Input tied to RP35
100010 = Input tied to RP34
100001 = Input tied to RP33
100000 = Input tied to RP32
•
•
•
00000 = Input tied to RP0

**REGISTER 10-14: RPINR34: PERIPHERAL PIN SELECT INPUT REGISTER 34**

| U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
|---|---|---|---|---|---|---|---|
| — | — | — | — | — | — | — | — |
| bit 15 | | | | | | | bit 8 |

| U-0 | U-0 | R/W-1 | R/W-1 | R/W-1 | R/W-1 | R/W-1 | R/W-1 |
|---|---|---|---|---|---|---|---|
| — | — | SYNCI2R5 | SYNCI2R4 | SYNCI2R3 | SYNCI2R2 | SYNCI2R1 | SYNCI2R0 |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as ‘0’ | |
| -n = Value at POR | ‘1’ = Bit is set | ‘0’ = Bit is cleared | x = Bit is unknown |

bit 15-6 **Unimplemented:** Read as ‘0’

bit 5-0 **SYNCI2R<5:0>:** Assign PWM Master Time Base External Synchronization Signal to the Corresponding RPn Pin bits

111111 = Input tied to Vss
100011 = Input tied to RP35
100010 = Input tied to RP34
100001 = Input tied to RP33
100000 = Input tied to RP32
•
•
•
00000 = Input tied to RP0

**REGISTER 10-15: RPOR0: PERIPHERAL PIN SELECT OUTPUT REGISTER 0**

| U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| — | — | RP1R5 | RP1R4 | RP1R3 | RP1R2 | RP1R1 | RP1R0 |
| bit 15 | | | | | | | bit 8 |

| U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| — | — | RP0R5 | RP0R4 | RP0R3 | RP0R2 | RP0R1 | RP0R0 |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as ‘0’ | |
| -n = Value at POR | ‘1’ = Bit is set | ‘0’ = Bit is cleared | x = Bit is unknown |

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP1R<5:0>:** Peripheral Output Function is Assigned to RP1 Output Pin bits (see Table 10-2 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP0R<5:0>:** Peripheral Output Function is Assigned to RP0 Output Pin bits (see Table 10-2 for peripheral function numbers)

**REGISTER 14-1: OCxCON: OUTPUT COMPARE x CONTROL REGISTER (x = 1, 2)**

| U-0 | U-0 | R/W-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
|---|---|---|---|---|---|---|---|
| — | — | OCSIDL | — | — | — | — | — |
| bit 15 | | | | | | | bit 8 |

| U-0 | U-0 | U-0 | R-0, HC | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| — | — | — | OCFLT | OCTSEL | OCM2 | OCM1 | OCM0 |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | HC = Hardware Clearable bit | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' | |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared | x = Bit is unknown |

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **OCSIDL:** Stop Output Compare in Idle Mode Control bit
1 = Output Compare x halts in CPU Idle mode
0 = Output Compare x continues to operate in CPU Idle mode

bit 12-5 **Unimplemented:** Read as '0'

bit 4 **OCFLT:** PWM Fault Condition Status bit
1 = PWM Fault condition has occurred (cleared in hardware only)
0 = No PWM Fault condition has occurred (this bit is only used when OCM<2:0> = 111)

bit 3 **OCTSEL:** Output Compare Timer Select bit
1 = Timer3 is the clock source for Output Compare x
0 = Timer2 is the clock source for Output Compare x

bit 2-0 **OCM<2:0>:** Output Compare Mode Select bits
111 = PWM mode on OCx, Fault pin is enabled
110 = PWM mode on OCx, Fault pin is disabled
101 = Initializes OCx pin low, generates continuous output pulses on OCx pin
100 = Initializes OCx pin low, generates single output pulse on OCx pin
011 = Compare event toggles OCx pin
010 = Initializes OCx pin high, compare event forces OCx pin low
001 = Initializes OCx pin low, compare event forces OCx pin high
000 = Output compare channel is disabled

## 15.2 Feature Description

The PWM module is designed for applications that require:

- High-resolution at high PWM frequencies
- The ability to drive Standard, Edge-Aligned, Center-Aligned Complementary mode, and Push-Pull mode outputs
- The ability to create multiphase PWM outputs

For Center-Aligned mode, the duty cycle, period phase and dead-time resolutions will be 8.32 ns.

Two common, medium power converter topologies are push-pull and half-bridge. These designs require the PWM output signal to be switched between alternate pins, as provided by the Push-Pull PWM mode.

Phase-shifted PWM describes the situation where each PWM generator provides outputs, but the phase relationship between the generator outputs is specifiable and changeable.

Multiphase PWM is often used to improve DC/DC Converter load transient response, and reduce the size of output filter capacitors and inductors. Multiple DC/DC Converters are often operated in parallel, but phase-shifted in time. A single PWM output operating at 250 kHz has a period of 4 μs, but an array of four PWM channels, staggered by 1 μs each, yields an effective switching frequency of 1 MHz. Multiphase PWM applications typically use a fixed-phase relationship.

Variable phase PWM is useful in Zero Voltage Transition (ZVT) power converters. Here, the PWM duty cycle is always 50%, and the power flow is controlled by varying the relative phase shift between the two PWM generators.

**REGISTER 16-3: SPIxCON2: SPIx CONTROL REGISTER 2**

| R/W-0 | R/W-0 | R/W-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
|---|---|---|---|---|---|---|---|
| FRMEN | SPIFSD | FRMPOL | — | — | — | — | — |
| bit 15 | | | | | | | bit 8 |

| U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | R/W-0 | U-0 |
|---|---|---|---|---|---|---|---|
| — | — | — | — | — | — | FRMDLY | — |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as ‘0’ | |
| -n = Value at POR | ‘1’ = Bit is set | ‘0’ = Bit is cleared | x = Bit is unknown |

bit 15 **FRMEN**: Framed SPIx Support bit
1 = Framed SPIx support is enabled ($\overline{SSx}$ pin used as frame sync pulse input/output)
0 = Framed SPIx support is disabled

bit 14 **SPIFSD**: SPIx Frame Sync Pulse Direction Control bit
1 = Frame sync pulse input (slave)
0 = Frame sync pulse output (master)

bit 13 **FRMPOL**: Frame Sync Pulse Polarity bit
1 = Frame sync pulse is active-high
0 = Frame sync pulse is active-low

bit 12-2 **Unimplemented:** Read as ‘0’

bit 1 **FRMDLY**: Frame Sync Pulse Edge Select bit
1 = Frame sync pulse coincides with first bit clock
0 = Frame sync pulse precedes first bit clock

bit 0 **Unimplemented:** This bit must not be set to ‘1’ by the user application

**NOTES:**

## 24.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

### Absolute Maximum Ratings(1)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on $V_{DD}$ with respect to $V_{SS}$ ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to $V_{SS}$(3) ..... -0.3V to ($V_{DD}$ + 0.3V)
Voltage on any 5V tolerant pin with respect to $V_{SS}$, when $V_{DD} \geq 3.0V$(3) ..... -0.3V to +5.6V
Voltage on any 5V tolerant pin with respect to Vss, when $V_{DD} < 3.0V$(3) ..... -0.3V to ($V_{DD}$ + 0.3V)
Maximum current out of $V_{SS}$ pin ..... 300 mA
Maximum current into $V_{DD}$ pin(2) ..... 250 mA
Maximum current sourced/sunk by any 4x I/O pin ..... 15 mA
Maximum current sourced/sunk by any 8x I/O pin ..... 25 mA
Maximum current sourced/sunk by any 16x I/O pin ..... 45 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports(2) ..... 200mA

**Note 1:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

**2:** Maximum allowable current is a function of device maximum power dissipation (see Table 24-2).

**3:** See the **“Pin Diagrams”** section for 5V tolerant pins.

**TABLE 24-17: PLL CLOCK TIMING SPECIFICATIONS ($V_{DD}$ = 3.0V TO 3.6V)**

| AC CHARACTERISTICS | | | Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)<br>Operating temperature -40°C ≤ TA ≤ +85°C for Industrial<br>-40°C ≤ TA ≤ +125°C for Extended | | | | |
|---|---|---|---|---|---|---|---|
| **Param No.** | **Symbol** | **Characteristic** | **Min** | **Typ(1)** | **Max** | **Units** | **Conditions** |
| OS50 | FPLLI | PLL Voltage Controlled Oscillator (VCO) Input Frequency Range | 0.8 | — | 8 | MHz | ECPLL, XTPLL modes |
| OS51 | FSYS | On-Chip VCO System Frequency | 100 | — | 200 | MHz | |
| OS52 | TLOCK | PLL Start-up Time (Lock Time) | 0.9 | 1.5 | 3.1 | mS | |
| OS53 | DCLK | CLKO Stability (Jitter)(2) | -3 | 0.5 | 3 | % | Measured over 100 ms period |

**Note 1:** Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested in manufacturing.

**2:** These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time bases or communication clocks use this formula:

$$Peripheral\ Clock\ Jitter = \frac{DCLK}{\sqrt{\left(\frac{FOSC}{Peripheral\ Bit\ Rate\ Clock}\right)}}$$

For example: FOSC = 32 MHz, DCLK = 3%, SPI bit rate clock (i.e., SCKx) is 2 MHz.

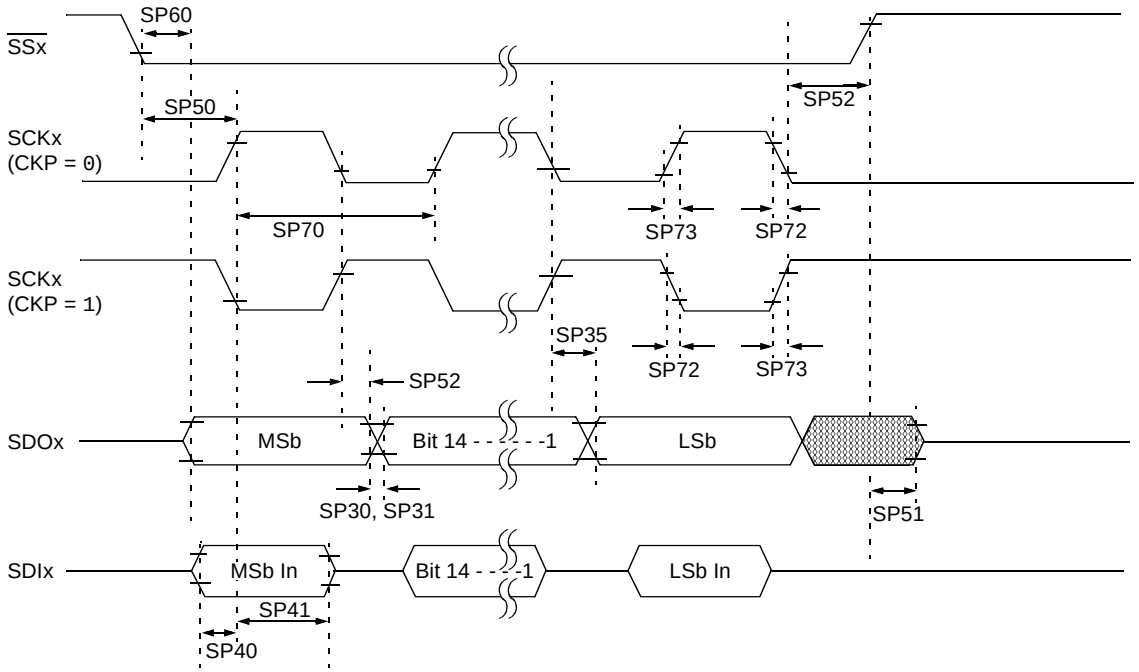
$$SPI\ SCK\ Jitter = \left\lceil \frac{DCLK}{\sqrt{\left(\frac{32\ MHz}{2\ MHz}\right)}} \right\rceil = \left\lceil \frac{3\%}{\sqrt{16}} \right\rceil = \left\lceil \frac{3\%}{4} \right\rceil = 0.75\%$$

**TABLE 24-18: AUXILIARY PLL CLOCK TIMING SPECIFICATIONS ($V_{DD}$ = 3.0V TO 3.6V)**

| AC CHARACTERISTICS | | | Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)<br>Operating temperature -40°C ≤ TA ≤ +85°C for Industrial<br>-40°C ≤ TA ≤ +125°C for Extended | | | | |
|---|---|---|---|---|---|---|---|
| **Param No.** | **Symbol** | **Characteristic** | **Min** | **Typ(1)** | **Max** | **Units** | **Conditions** |
| OS56 | FHPOUT | On-Chip 16x PLL CCO Frequency | 112 | 118 | 120 | MHz | |
| OS57 | FHPIN | On-Chip 16x PLL Phase Detector Input Frequency | 7.0 | 7.37 | 7.5 | MHz | |
| OS58 | TSU | Frequency Generator Lock Time | — | — | 10 | µs | |

**Note 1:** Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested in manufacturing.

**FIGURE 24-16: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS**




**Note:** Refer to Figure 24-1 for load conditions.

**TABLE 25-4: DC CHARACTERISTICS: POWER-DOWN CURRENT ($I_{PD}$)**

| DC CHARACTERISTICS | | | Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)<br>Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature | | | |
|---|---|---|---|---|---|---|
| **Parameter No.** | **Typical(1)** | **Max** | **Units** | **Conditions** | | |
| **Power-Down Current ($I_{PD}$)(2,4)** | | | | | | |
| HDC60e | 1000 | 2000 | μA | +150°C | 3.3V | Base Power-Down Current |
| HDC61c | 100 | 110 | μA | +150°C | 3.3V | Watchdog Timer Current: $\Delta I_{WDT}$(3) |

**Note 1:** Data in the Typical column is at 3.3V, +25°C unless otherwise stated.

**2:** $I_{PD}$ (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to $V_{SS}$
- $\overline{MCLR}$ = $V_{DD}$, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all ones)
- The VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to stand-by while the device is in Sleep mode)
- JTAG disabled

**3:** The Δ current is the additional current consumed when the WDT module is enabled. This current should be added to the base $I_{PD}$ current.

**4:** These currents are measured on the device containing the most memory in this family.

## 26.0 50 MIPS ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 electrical characteristics for devices operating at 50 MIPS.

The specifications for 50 MIPS are identical to those shown in **Section 24.0 "Electrical Characteristics"**, with the exception of the parameters listed in this section.

Parameters in this section begin with the letter "M", which denotes 50 MIPS operation. For example, Parameter DC29a in **Section 24.0 "Electrical Characteristics"**, is the up to 40 MIPS operation equivalent of MDC29a.

Absolute maximum ratings for the dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 50 MIPS devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

### Absolute Maximum Ratings(1)

Ambient temperature under bias ..... -40°C to +85°C
Storage temperature ..... -65°C to +150°C
Voltage on $V_{DD}$ with respect to $V_{SS}$ ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to $V_{SS}$(3) ..... -0.3V to ($V_{DD}$ + 0.3V)
Voltage on any 5V tolerant pin with respect to $V_{SS}$, when Vdd ≥ 3.0V(3) ..... -0.3V to +5.6V
Voltage on any 5V tolerant pin with respect to Vss, when $V_{DD}$ < 3.0V(3) ..... -0.3V to ($V_{DD}$ + 0.3V)
Maximum current out of $V_{SS}$ pin ..... 300 mA
Maximum current into $V_{DD}$ pin(2) ..... 250 mA
Maximum current sourced/sunk by any 4x I/O pin ..... 15 mA
Maximum current sourced/sunk by any 8x I/O pin ..... 25 mA
Maximum current sourced/sunk by any 16x I/O pin ..... 45 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports(2) ..... 200 mA

**Note 1:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

**2:** Maximum allowable current is a function of device maximum power dissipation (see Table 24-2).

**3:** See the **"Pin Diagrams"** section for 5V tolerant pins.

**TABLE 26-3: DC CHARACTERISTICS: IDLE CURRENT ($I_{IDLE}$)**

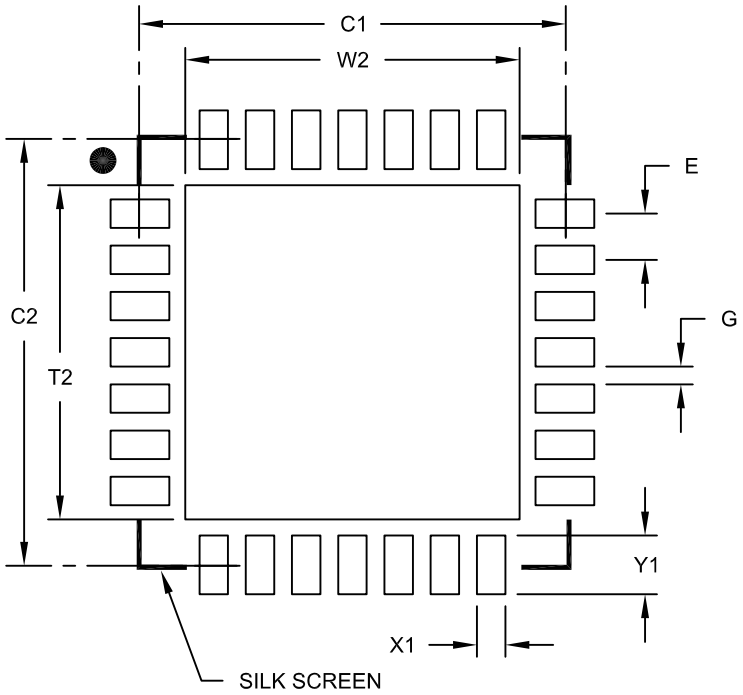
| DC CHARACTERISTICS | | | Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)<br>Operating temperature -40°C ≤ TA ≤ +85°C for Industrial | | | |
|---|---|---|---|---|---|---|
| **Parameter No.** | **Typical** | **Max** | **Units** | **Conditions** | | |
| **Idle Current ($I_{IDLE}$): Core Off, Clock On Base Current(1)** | | | | | | |
| MDC45d | 64 | 105 | mA | -40°C | 3.3V | 50 MIPS |
| MDC45a | 64 | 105 | mA | +25°C | | |
| MDC45b | 64 | 105 | mA | +85°C | | |

**Note 1:** Base Idle current ($I_{IDLE}$) is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD, WDT and FSCM are disabled
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- The NVMSIDL bit (NVMCON<12>) = 1 (i.e., Flash regulator is set to standby while the device is in Idle mode)
- JTAG is disabled

### 28-Lead Plastic Quad Flat, No Lead Package (MM) – 6x6x0.9 mm Body [QFN-S] with 0.40 mm Contact Length

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging




RECOMMENDED LAND PATTERN

| Units | | MILLIMETERS | | |
|---|---|---|---|---|
| Dimension Limits | | MIN | NOM | MAX |
| Contact Pitch | E | | 0.65 BSC | |
| Optional Center Pad Width | W2 | | | 4.70 |
| Optional Center Pad Length | T2 | | | 4.70 |
| Contact Pad Spacing | C1 | | 6.00 | |
| Contact Pad Spacing | C2 | | 6.00 | |
| Contact Pad Width (X28) | X1 | | | 0.40 |
| Contact Pad Length (X28) | Y1 | | | 0.85 |
| Distance Between Pads | G | 0.25 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2124A